<u>S/N 10/623,788</u> <u>PATENT</u>

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Leonard Forbes et al. Examiner: Pamela E. Perkins

Serial No.: 10/623,788 Group Art Unit: 2822

Filed: July 21, 2003 Docket No.: 1303.109US1

STRAINED SEMICONDUCTOR BY FULL WAFER BONDING

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Mail Stop Amendment Commissioner for Patents

P.O. Box 1450

Fitle:

Alexandria, VA 22313-1450

This responds to the Office Action dated on September 18, 2006. Please amend the above-identified patent application as follows.